

SECTION A-A

Notes: (Unless Otherwise Specified).

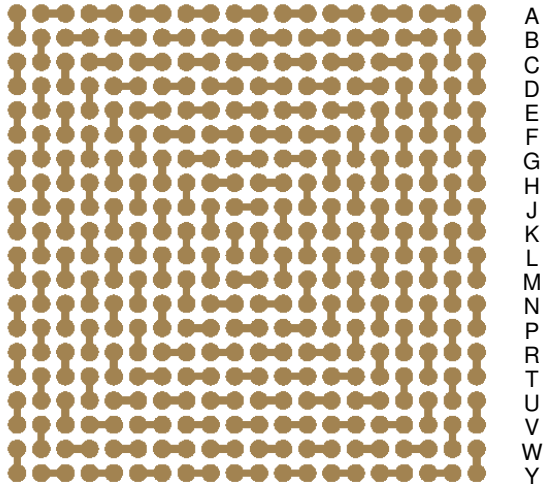
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.25mm [10 MIL].
- 5) PAD Cu DIAMETER: 0.355mm [14 MIL].
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA400T.5C-DC209	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA400T.5C-DC209D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA400T.5-DC209	Sn63/Pb37	NO	NO	NO
BGA400T.5-DC209D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE		<b>TopLine</b> <sup>®</sup>							
X.XX	+/- 0.01	DRAWN J. Hines		10/04/2011						TITLE <b>BGA400T.5-DC209 DAISY CHAIN DUMMY</b>			
X.XXX	+/- 0.005	ENG				SCALE 8:1		SIZE A					
X.XXXX	+/- 0.0005	MFG											
ANGLES +/- 0.5°		QA											
ALL DIMENSIONS IN ☐ INCHES    ☒ MILLIMETERS		CUST											
THIRD ANGLE PROJECTION		REVISED											
		DO NOT SCALE DRAWING										SHEET 1 OF 2	

### BALL VIEW

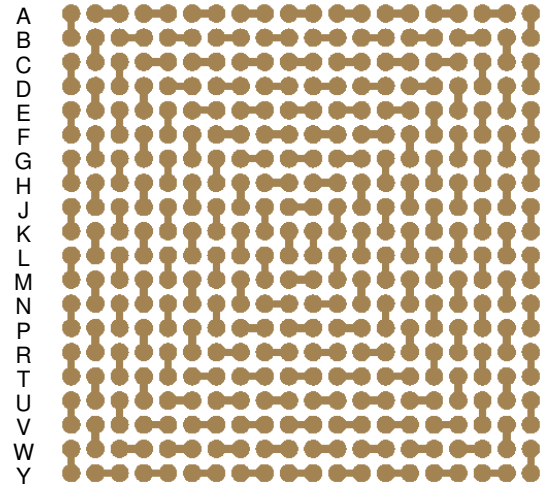
20 18 16 14 12 10 8 6 4 2  
19 17 15 13 11 9 7 5 3 1



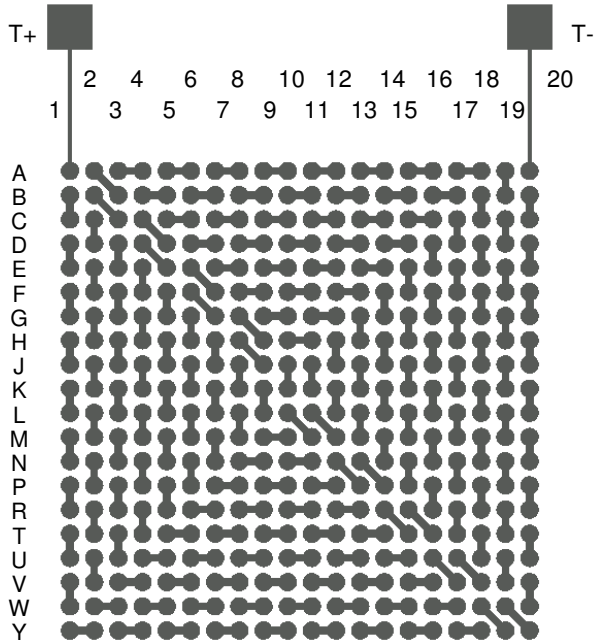
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Y

### BOTTOM SIDE (TOP X-RAY VIEW)

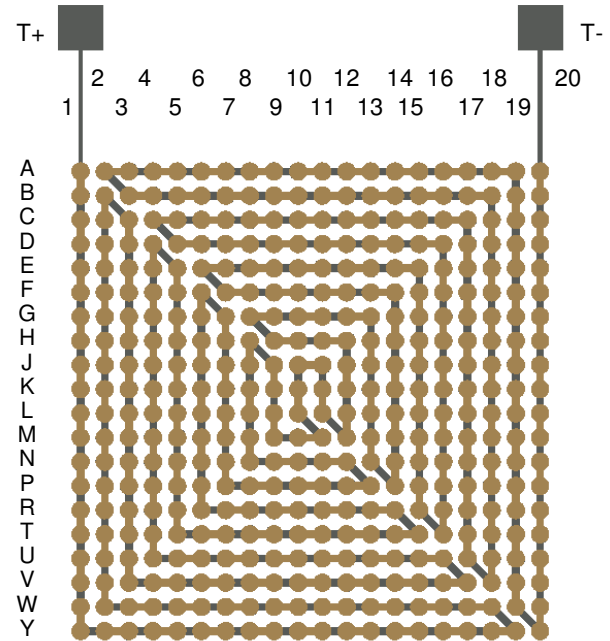
2 4 6 8 10 12 14 16 18 20  
1 3 5 7 9 11 13 15 17 19



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TEST VEHICLE BOARD



AFTER MOUNTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm [14 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.25mm [10 MIL].



TITLE			
BGA400T.5-DC209 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
8:1	A	552090	A
DO NOT SCALE DRAWING			SHEET 2 OF 2